

Axial Lead Rectifiers

1N5820, 1N5821, 1N5822

1N5820 and 1N5822 are Preferred Devices

This series employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features chrome barrier metal, epitaxial construction with oxide passivation and metal overlap contact. Ideally suited for use as rectifiers in low-voltage, high-frequency inverters, free wheeling diodes, and polarity protection diodes.

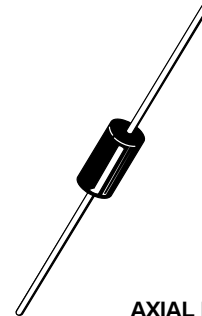
Features

- Extremely Low V_F
- Low Power Loss/High Efficiency
- Low Stored Charge, Majority Carrier Conduction
- Shipped in plastic bags, 500 per bag
- Available in Tape and Reel, 1500 per reel, by adding a "RL" suffix to the part number
- Pb-Free Packages are Available*

Mechanical Characteristics:

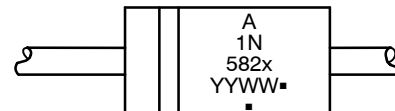
- Case: Epoxy, Molded
- Weight: 1.1 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Cathode indicated by Polarity Band

SCHOTTKY BARRIER RECTIFIERS 3.0 AMPERES 20, 30, 40 VOLTS



AXIAL LEAD
CASE 267-05
(DO-201AD)
STYLE 1

MARKING DIAGRAM



A = Assembly Location
 1N582x = Device Code
 x = 0, 1, or 2
 YY = Year
 WW = Work Week
 ■ = Pb-Free Package
 (Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

1N5820, 1N5821, 1N5822

MAXIMUM RATINGS

Rating	Symbol	1N5820	1N5821	1N5822	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	20	30	40	V
Non-Repetitive Peak Reverse Voltage	V_{RSM}	24	36	48	V
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	V
Average Rectified Forward Current (Note 1) $V_{R(equiv)} \leq 0.2 V_{R(dc)}$, $T_L = 95^\circ\text{C}$ ($R_{\theta JA} = 28^\circ\text{C/W}$, P.C. Board Mounting, see Note 5)	I_O	3.0			A
Ambient Temperature Rated $V_{R(dc)}$, $P_{F(AV)} = 0$ $R_{\theta JA} = 28^\circ\text{C/W}$	T_A	90	85	80	$^\circ\text{C}$
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, half wave, single phase 60 Hz, $T_L = 75^\circ\text{C}$)	I_{FSM}	80 (for one cycle)			A
Operating and Storage Junction Temperature Range (Reverse Voltage applied)	T_J, T_{stg}	-65 to +125			$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

*THERMAL CHARACTERISTICS (Note 5)

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	28	$^\circ\text{C/W}$

*ELECTRICAL CHARACTERISTICS ($T_L = 25^\circ\text{C}$ unless otherwise noted) (Note 1)

Characteristic	Symbol	1N5820	1N5821	1N5822	Unit
Maximum Instantaneous Forward Voltage (Note 2) ($i_F = 1.0$ Amp) ($i_F = 3.0$ Amp) ($i_F = 9.4$ Amp)	V_F	0.370 0.475 0.850	0.380 0.500 0.900	0.390 0.525 0.950	V
Maximum Instantaneous Reverse Current @ Rated dc Voltage (Note 2) $T_L = 25^\circ\text{C}$ $T_L = 100^\circ\text{C}$	i_R	2.0 20	2.0 20	2.0 20	mA

1. Lead Temperature reference is cathode lead 1/32" from case.

2. Pulse Test: Pulse Width = 300 μs , Duty Cycle = 2.0%.

*Indicates JEDEC Registered Data for 1N5820-22.

NOTE 3 — DETERMINING MAXIMUM RATINGS

Reverse power dissipation and the possibility of thermal runaway must be considered when operating this rectifier at reverse voltages above $0.1 V_{RWM}$. Proper derating may be accomplished by use of equation (1).

$$T_{A(max)} = T_{J(max)} - R_{\theta JA} P_{F(AV)} - R_{\theta JA} P_{R(AV)} \quad (1)$$

where $T_{A(max)}$ = Maximum allowable ambient temperature
 $T_{J(max)}$ = Maximum allowable junction temperature (125°C or the temperature at which thermal runaway occurs, whichever is lowest)
 $P_{F(AV)}$ = Average forward power dissipation
 $P_{R(AV)}$ = Average reverse power dissipation
 $R_{\theta JA}$ = Junction-to-ambient thermal resistance

Figures 1, 2, and 3 permit easier use of equation (1) by taking reverse power dissipation and thermal runaway into consideration. The figures solve for a reference temperature as determined by equation (2).

$$T_R = T_{J(max)} - R_{\theta JA} P_{R(AV)} \quad (2)$$

Substituting equation (2) into equation (1) yields:

$$T_{A(max)} = T_R - R_{\theta JA} P_{F(AV)} \quad (3)$$

Inspection of equations (2) and (3) reveals that T_R is the ambient temperature at which thermal runaway occurs or where $T_J = 125^\circ\text{C}$, when forward power is zero. The transition from one boundary condition to the other is evident on the curves of Figures 1, 2, and 3 as a difference in the rate of change of the slope in the vicinity of 115°C . The data of Figures 1, 2, and 3 is based upon dc conditions. For

use in common rectifier circuits, Table 1 indicates suggested factors for an equivalent dc voltage to use for conservative design, that is:

$$V_{R(equiv)} = V_{(FM)} \times F \quad (4)$$

The factor F is derived by considering the properties of the various rectifier circuits and the reverse characteristics of Schottky diodes.

EXAMPLE: Find $T_{A(max)}$ for 1N5821 operated in a 12-volt dc supply using a bridge circuit with capacitive filter such that $I_{DC} = 2.0 \text{ A}$ ($I_{F(AV)} = 1.0 \text{ A}$), $I_{(FM)}/I_{(AV)} = 10$, Input Voltage = $10 V_{(rms)}$, $R_{\theta JA} = 40^\circ\text{C/W}$.

Step 1. Find $V_{R(equiv)}$. Read $F = 0.65$ from Table 1,

$$\therefore V_{R(equiv)} = (1.41) (10) (0.65) = 9.2 \text{ V.}$$

Step 2. Find T_R from Figure 2. Read $T_R = 108^\circ\text{C}$

$$@ V_R = 9.2 \text{ V and } R_{\theta JA} = 40^\circ\text{C/W.}$$

Step 3. Find $P_{F(AV)}$ from Figure 6. **Read $P_{F(AV)} = 0.85 \text{ W}$

$$@ \frac{I_{(FM)}}{I_{(AV)}} = 10 \text{ and } I_{F(AV)} = 1.0 \text{ A.}$$

Step 4. Find $T_{A(max)}$ from equation (3).

$$T_{A(max)} = 108 - (0.85) (40) = 74^\circ\text{C.}$$

**Values given are for the 1N5821. Power is slightly lower for the 1N5820 because of its lower forward voltage, and higher for the 1N5822. Variations will be similar for the MBR-prefix devices, using $P_{F(AV)}$ from Figure 6.

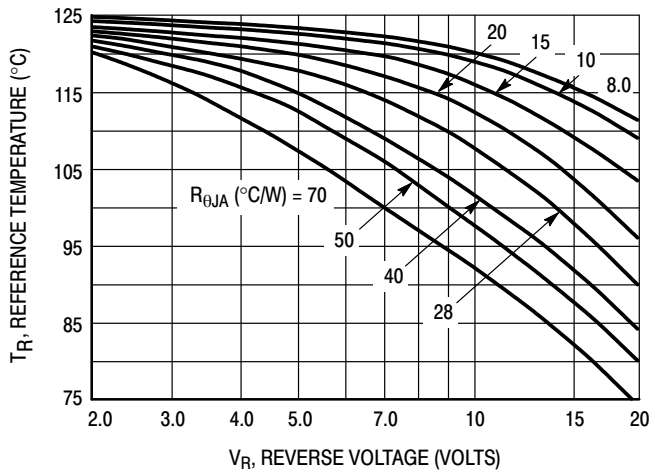
Table 1. Values for Factor F

Circuit	Half Wave		Full Wave, Bridge		Full Wave, Center Tapped*†	
	Resistive	Capacitive*	Resistive	Capacitive	Resistive	Capacitive
Sine Wave	0.5	1.3	0.5	0.65	1.0	1.3
Square Wave	0.75	1.5	0.75	0.75	1.5	1.5

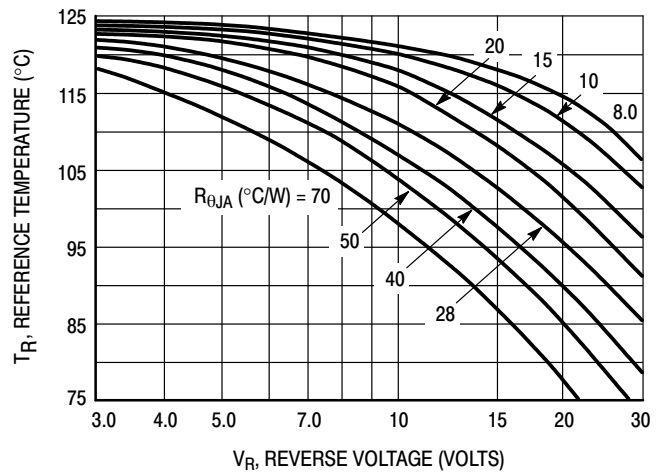
*Note that $V_{R(PK)} \approx 2.0 V_{in(PK)}$.

†Use line to center tap voltage for V_{in} .

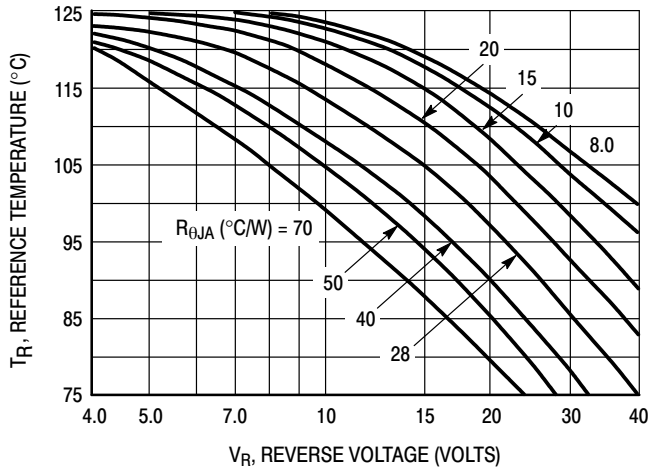
1N5820, 1N5821, 1N5822



**Figure 1. Maximum Reference Temperature
1N5820**



**Figure 2. Maximum Reference Temperature
1N5821**



**Figure 3. Maximum Reference Temperature
1N5822**

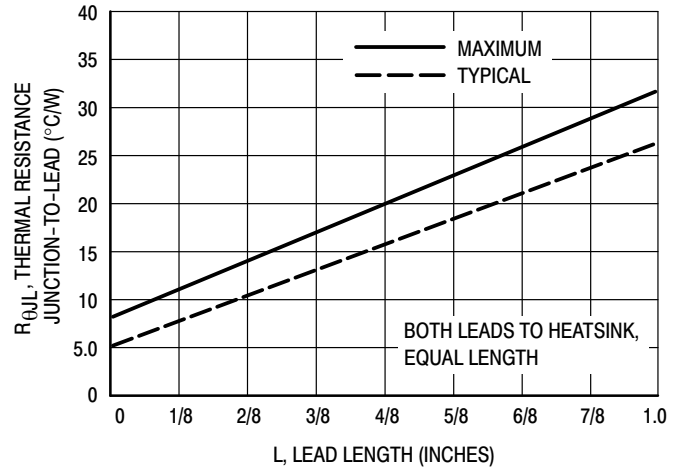


Figure 4. Steady-State Thermal Resistance

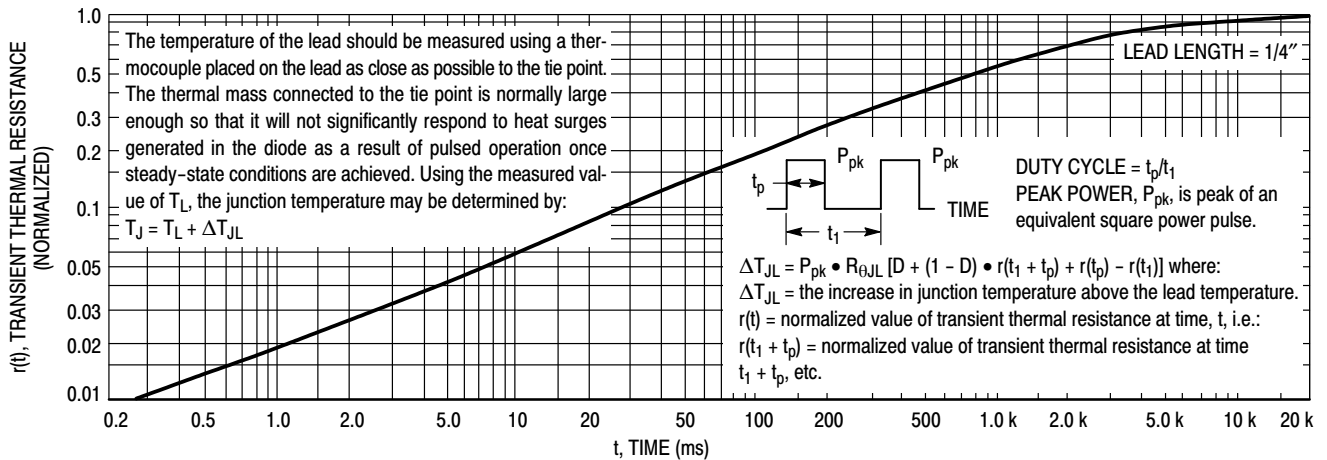


Figure 5. Thermal Response

1N5820, 1N5821, 1N5822

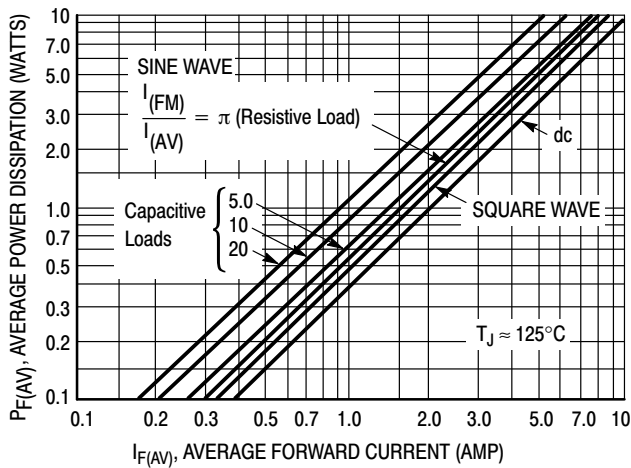
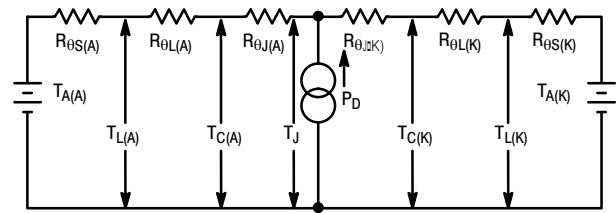


Figure 6. Forward Power Dissipation 1N5820-22

NOTE 4 – APPROXIMATE THERMAL CIRCUIT MODEL



Use of the above model permits junction to lead thermal resistance for any mounting configuration to be found. For a given total lead length, lowest values occur when one side of the rectifier is brought as close as possible to the heat sink. Terms in the model signify:

T_A = Ambient Temperature T_C = Case Temperature
 T_L = Lead Temperature T_J = Junction Temperature
 $R_{\theta S}$ = Thermal Resistance, Heatsink to Ambient
 $R_{\theta L}$ = Thermal Resistance, Lead-to-Heatsink
 $R_{\theta J}$ = Thermal Resistance, Junction-to-Case
 P_D = Total Power Dissipation = $P_F + P_R$
 P_F = Forward Power Dissipation
 P_R = Reverse Power Dissipation
(Subscripts (A) and (K) refer to anode and cathode sides, respectively.) Values for thermal resistance components are:

$R_{\theta L} = 42^\circ\text{C/W/in}$ typically and 48°C/W/in maximum

$R_{\theta J} = 10^\circ\text{C/W}$ typically and 16°C/W maximum

The maximum lead temperature may be found as follows:

$$T_L = T_{J(\max)} - \Delta T_{JL}$$

$$\text{where } \Delta T_{JL} \approx R_{\theta JL} \cdot P_D$$

NOTE 5 — MOUNTING DATA

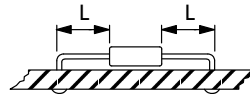
Data shown for thermal resistance junction-to-ambient ($R_{\theta JA}$) for the mountings shown is to be used as typical guideline values for preliminary engineering, or in case the tie point temperature cannot be measured.

TYPICAL VALUES FOR $R_{\theta JA}$ IN STILL AIR

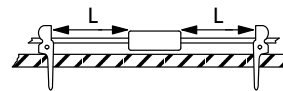
Mounting Method	Lead Length, L (in)				$R_{\theta JA}$
	1/8	1/4	1/2	3/4	
1	50	51	53	55	$^\circ\text{C/W}$
2	58	59	61	63	$^\circ\text{C/W}$
3	28				$^\circ\text{C/W}$

Mounting Method 1

P.C. Board where available copper surface is small.



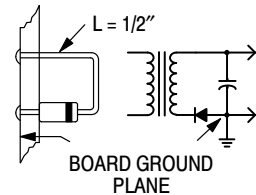
Mounting Method 2



VECTOR PUSH-IN
TERMINALS T-28

Mounting Method 3

P.C. Board with 2-1/2, x 2-1/2, copper surface.



1N5820, 1N5821, 1N5822

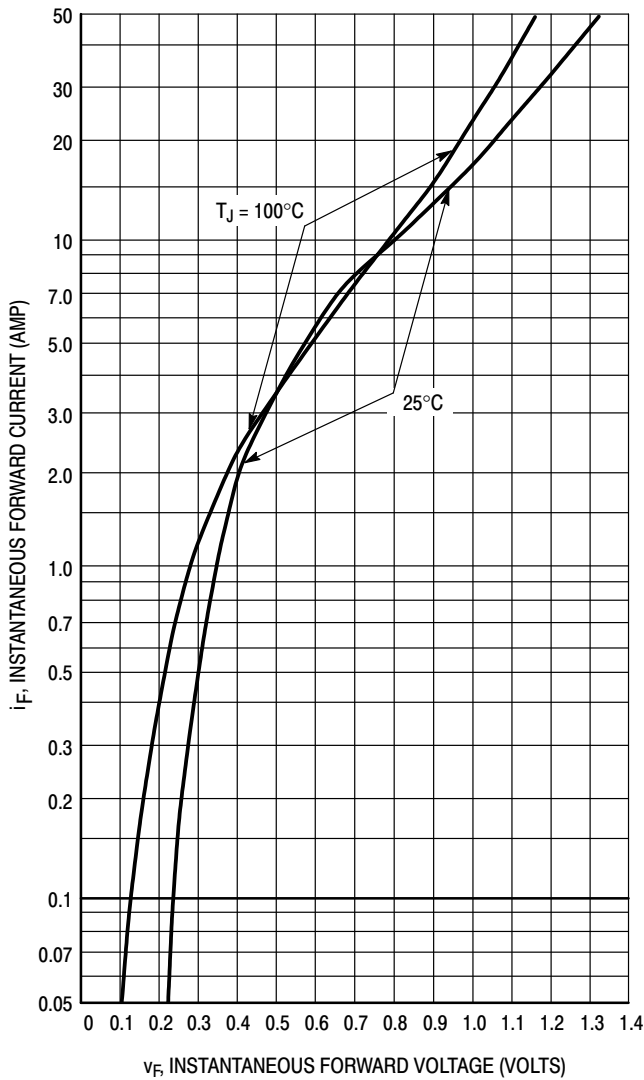


Figure 7. Typical Forward Voltage

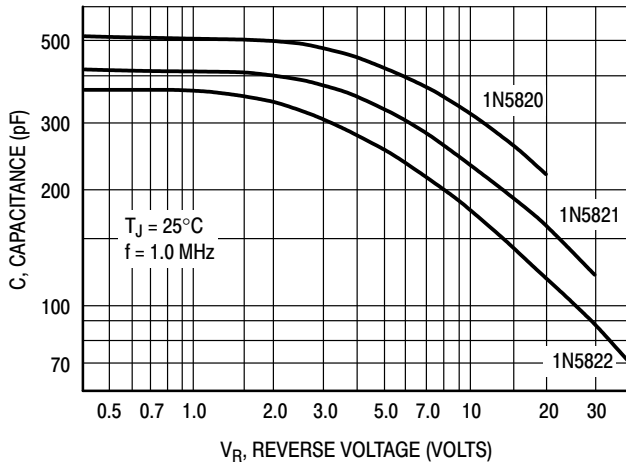


Figure 10. Typical Capacitance

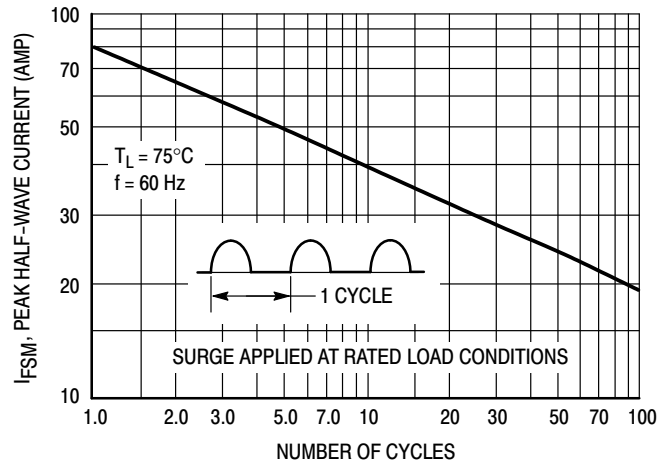


Figure 8. Maximum Non-Repetitive Surge Current

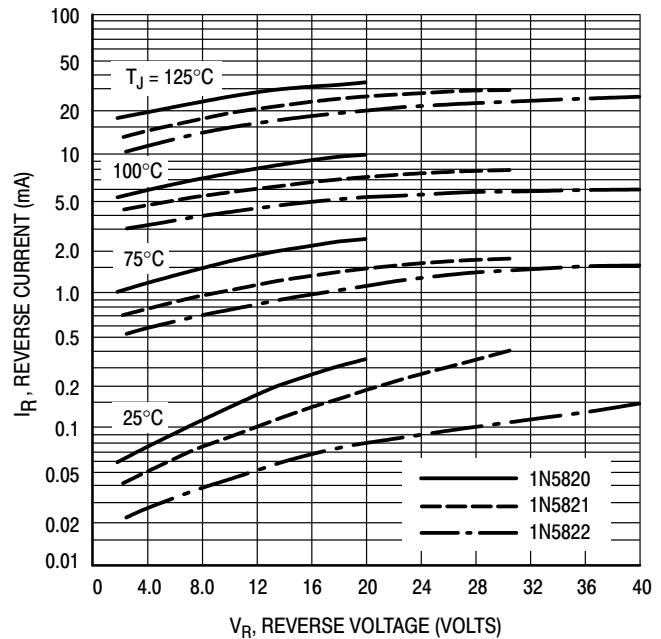


Figure 9. Typical Reverse Current

NOTE 6 — HIGH FREQUENCY OPERATION

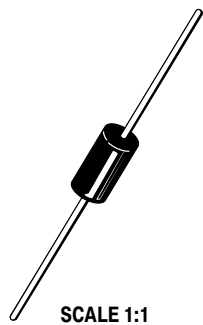
Since current flow in a Schottky rectifier is the result of majority carrier conduction, it is not subject to junction diode forward and reverse recovery transients due to minority carrier injection and stored charge. Satisfactory circuit analysis work may be performed by using a model consisting of an ideal diode in parallel with a variable capacitance. (See Figure 10.)

1N5820, 1N5821, 1N5822

ORDERING INFORMATION

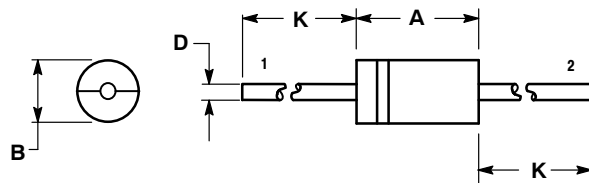
Device	Package	Shipping†
1N5820	Axial Lead	500 Units/Bag
1N5820G	Axial Lead (Pb-Free)	500 Units/Bag
1N5820RL	Axial Lead	1500/Tape & Reel
1N5820RLG	Axial Lead (Pb-Free)	1500/Tape & Reel
1N5821	Axial Lead	500 Units/Bag
1N5821G	Axial Lead (Pb-Free)	500 Units/Bag
1N5821RL	Axial Lead	1500/Tape & Reel
1N5821RLG	Axial Lead (Pb-Free)	1500/Tape & Reel
1N5822	Axial Lead	500 Units/Bag
1N5822G	Axial Lead (Pb-Free)	500 Units/Bag
1N5822RL	Axial Lead	1500/Tape & Reel
1N5822RLG	Axial Lead (Pb-Free)	1500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



AXIAL LEAD
CASE 267-05
ISSUE G

DATE 06 JUN 2000



NOTES:

1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 267-04 OBSOLETE, NEW STANDARD 267-05.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.287	0.374	7.30	9.50
B	0.189	0.209	4.80	5.30
D	0.047	0.051	1.20	1.30
K	1.000	---	25.40	---

STYLE 1:
PIN 1: CATHODE (POLARITY BAND)
2: ANODE

STYLE 2:
NO POLARITY

DOCUMENT NUMBER:	98ASB42170B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	AXIAL LEAD	PAGE 1 OF 1

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales